

**Electronic Patent Application Fee Transmittal**

<b>Application Number:</b>	10552540
<b>Filing Date:</b>	11-Oct-2005
<b>Title of Invention:</b>	THERMOSETTING RESIN COMPOSITION, MULTILAYER BODY USING SAME, AND CIRCUIT BOARD
<b>First Named Inventor/Applicant Name:</b>	Shigeru Tanaka
<b>Filer:</b>	Dariush G. Adli/Reynaldo Gallardo
<b>Attorney Docket Number:</b>	81844.0044

Filed as Large Entity

## **U.S. National Stage under 35 USC 371 Filing Fees**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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### Basic Filing:

Pages:

### Claims:

**Miscellaneous-Filing:**

**Petition:**

## Patent-Appeals-and-Interference:

### Post-Allowance-and-Post-Issuance:

Utility Appl issue fee	1501	1	1510	1510
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Extension-of-Time:</b>				
<b>Miscellaneous:</b>				
Printed copy of patent - no color	8001	4	3	12
<b>Total in USD (\$)</b>				<b>1822</b>